

ABSTRACT OF THE DISCLOSURE

A method and apparatus are provided for adhesive bonding of a backing plate for a sensor assembly to a vehicle window, especially a windscreen of a passenger car or truck. The backing plate has an adhesive layer and is heated at least in the area of the adhesive layer by a heating device until the adhesive layer is softened sufficiently to carry out adhesive bonding. The backing plate is transferred into a contact pressure device and the contact pressure device presses the backing plate with the adhesive layer on to the vehicle window for a predetermined length of time. In order to improve the usability of such a method in the context of mass production, it is provided that the heating device emits infrared radiation, heating of the adhesive layer being carried out until it has softened sufficiently by positioning the backing plate with the adhesive layer facing the heating device at a close spacing for a predetermined length of time.

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